

MP23DB02MM

Datasheet

MEMS audio sensor: digital microphone with multiple performance modes



RHLGA 5LD (3.5 x 2.65 x 0.98 mm)

Features

- Omnidirectional digital microphone
- Sensitivity: -26 dBFS ±1dB
- "Always-on" experience with low power consumption
- Multiple performance modes (low power, normal)
- Typical current consumption
 - 285 µA (low-power mode)
 - 800 μA (normal mode)
- 122 dBSPL acoustic overload point for all operative modes
- PDM single-bit output with option for stereo configuration
- RHLGA package
 - Bottom-port design
 - SMD-compliant
 - EMI-shielded
 - ECOPACK, RoHS and "Green" compliant

Applications

- Smartphones and handsets
- Laptop and notebook computers
- Wearable devices
- Digital still and video cameras
- Antitheft systems

Description

lectronics sales office

The MP23DB02MM is an ultra-compact, low-power, omnidirectional, digital MEMS microphone built with a capacitive sensing element and an IC interface with optional stereo configuration.

The sensing element, capable of detecting acoustic waves, is manufactured using a specialized silicon micromachining process dedicated to produce audio sensors.

The IC interface is manufactured using a CMOS process that allows designing a dedicated circuit able to provide a digital signal externally in PDM format.

The MP23DB02MM offers multiple performance modes enabled by different clock frequency ranges (power down, low power and normal mode). The device has a narrow sensitivity range of ± 1 dB, high SNR and low distortion for all operative modes.

The MP23DB02MM is available in a bottom-port, SMD-compliant, EMI-shielded package and is guaranteed to operate over an extended temperature range from -40 $^\circ$ C to +85 $^\circ$ C.

MP23DB02MM					
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Order code	MP23DB02MMTR				
Temp. range [°C]	-40 to +85				
Deeleene	RHLGA 5LD				
Package	(3.5 x 2.65 x 0.98) mm				
Packing	Tape and reel				

Product status link

1 Pin description

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Figure 1. Pin connections

Bottom View



Table 1. Pin description

Pin #	Pin name	Function
1	DOUT	Left/right PDM data output
2	L/R	Left/right channel selection
3 (ground ring)	GND	0 V supply
4	CLK	Synchronization input clock
5	VDD	Supply voltage

2 Acoustic and electrical specifications

2.1 Acoustic and electrical characteristics

The values listed in the table below are specified for Vdd = 1.8 V, Clock = 2.4 MHz, T = $25 \degree$ C, no load, unless otherwise noted.

Symbol	Parameter	Test condition	Min.	Typ. ⁽¹⁾	Max.	Unit
Vdd	Supply voltage		1.6		3.6	V
		Power-down mode	0		0.15	
f _{CLK}	Clock frequency range ⁽²⁾	Low-power mode	0.54	0.768	1.1	MHz
		Normal mode	1.5	2.4	3.3	
ldd	Current consumption in normal mode	Fc = 2.4 MHz		800		
iuu	Current consumption in low-power mode	Fc = 768 kHz		285		μA
lddPdn	Current consumption in power-down mode ⁽³⁾		2		5	
lcc	Short-circuit current		1		10	mA
V _{IOL}	Low-level logic input/output voltage	lout = 1 mA	-0.3		0.35xVdd	V
V _{IOH}	High-level logic input/output voltage	lout = 1 mA	0.65xVdd		Vdd+0.3	V
TWK	Wake-up time ⁽⁴⁾	guaranteed by design			20	ms
Roll-off	Frequency response	at -3 dB		35		Hz
Cload	DOUT load capacitance				100	pF
Тор	Operating temperature range		-40		+85	°C

Table 2. Acoustic and electrical characteristics

1. Typical specifications are not guaranteed.

2. Duty cycle: min = 40% max = 60%

3. Input clock in static mode

4. Time from the first clock edge to valid output data

The values listed in the table below are specified for Vdd = 1.8 V, Clock = 768 kHz, no load, T = 25 $^{\circ}$ C, unless otherwise noted.

Table 3. Low-power mode

Symbol	Parameter	Test condition	Min.	Typ. ⁽¹⁾	Max.	Unit
ldd	Current consumption			285		μA
So	Sensitivity	94 dBSPL @ 1 kHz	-27	-26	-25	dBFS
SNR	Signal-to-noise ratio	94 dBSPL @ 1 kHz A-weighted (20 Hz - 8 kHz)		64		dB(A)
THD		94 dBSPL @ 1 kHz		0.5		%
IND	Total harmonic distortion	120 dBSPL @ 1 kHz		4		70
AOP	Acoustic overload point			122		dBSPL
PSR	Power supply rejection	100 mVpp sinewave @ 217 Hz		-90		dBFS

1. Typical specifications are not guaranteed.

The values listed in the table below are specified for Vdd = 1.8 V, Clock = 2.4 MHz, no load, T = 25 $^{\circ}$ C, unless otherwise noted.

Table 4. Normal mo	de
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Symbol	Parameter	Test condition	Min.	Typ. ⁽¹⁾	Max.	Unit
ldd	Current consumption			800		μA
So	Sensitivity	94 dBSPL @ 1 kHz	-27	-26	-25	dBFS
SNR	Signal-to-noise ratio	94 dBSPL @ 1 kHz A-weighted (20 Hz - 8 kHz)		65		dB(A)
TUD	THD Total harmonic distortion	94 dBSPL @ 1 kHz		0.5		%
THD		120 dBSPL @ 1 kHz		4		%
AOP	Acoustic overload point			122		dBSPL
PSR	Power supply rejection	100 mVpp sinewave @ 217 Hz		-90		dBFS

1. Typical specifications are not guaranteed.

2.2 Timing characteristics

Table 5. Timing characteristics

Symbol	Description		Max.	Unit
T _{dv}	Delay time to valid data (Cload = 100 pF)		120	ns
T _{en}	Delay time to data driven 19		ns	
T _{dis}	Delay time to Hi-Z	4	17	ns





2.3 Frequency response

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Figure 3. Normalized frequency response

3 Absolute maximum ratings

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Stresses above those listed as "Absolute maximum ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device under these conditions is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Table 6. Absolute maximum ratings

Symbol	Ratings	Maximum value	Unit
Vdd	Supply voltage	-0.3 to 4.8	V
Vin	Input voltage on any control pin ⁽¹⁾	-0.3 to Vdd +0.3	V
T _{STG}	Storage temperature range	-40 to +125	°C
	(HBM) ANSI/ESDA/JEDEC JS001	±2000	
ESD (MM) EIA/JESD22-A115 ±200		±200	V
	(CDM) JESD22-C101		
ESD ⁽²⁾	Per IEC61000-4-2, 150 pF, 330 Ω direct contact to housing ±8000		V

1. Supply voltage on any pin should never exceed 4.8V

2. Bypass capacitor of 200nF or 1 µF (better) is highly recommended for ESD main clamp integrity.



This device is sensitive to mechanical shock, improper handling can cause permanent damage to the part.

This device is sensitive to electrostatic discharge (ESD), improper handling can cause permanent damage to the part.

4 Functionality

4.1 L/R channel selection

The L/R digital pad lets the user select the DOUT signal pattern as indicated in the following table. The L/R pin must be connected to Vdd or GND.

Table 7. L/R channel selection

L/R	CLK low	CLK high
GND	Data valid	High impedance
Vdd	High impedance	Data valid

Note: As the L/R pin is internally connected to GND via a 200 k Ω pull-down resistor, it is not mandatory to connect the pin itself to GND for the respective channel selection.

5 Application recommendations

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Figure 4. MP23DB02MM electrical connections







Power supply decoupling capacitors (100 nF ceramic, 1 μ F ceramic) should be placed as near as possible to pin 2 of the device (common design practice).

The L/R pin must be connected to Vdd or GND (refer to Table 7).

6 Package information

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In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

6.1 Soldering information

The RHLGA (3.5 x 2.65 x 0.98) mm package is also compliant with the RoHS and "Green" standards and is qualified for soldering heat resistance according to JEDEC J-STD-020. Landing pattern and soldering recommendations are available at www.st.com.



Figure 6. Recommended soldering profile limits

Table 8. Recommended soldering profile limits

Description	Parameter	Pb free
Average ramp rate	T _L to T _P	3 °C/sec max
Preheat		
Minimum temperature	T _{SMIN}	150 °C
Maximum temperature	T _{SMAX}	200 °C
Time (T _{SMIN} to T _{SMAX})	t _S	60 sec to 120 sec
Ramp-up rate	T_{SMAX} to T_{L}	
Time maintained above liquidus temperature	tL	60 sec to 150 sec
Liquidus temperature	TL	217 °C
Peak temperature	T _P	260 °C max
Time within 5 °C of actual peak temperature		20 sec to 40 sec
Ramp-down rate		6 °C/sec max
Time 25 °C (t25 °C) to peak temperature		8 minutes max

6.2 RHLGA-5L package information

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Figure 7. RHLGA 3.5 x 2.65 x 0.98 mm (metal cap) 5L package outline

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Dimensions are in millimeter unless otherwise specified General Tolerance is +/-0.15mm unless otherwise specified

OUTER DIMENSIONS

ITEM	DIMENSION [mm]	TOLERANCE [mm]
Length [L]	3.5	±0.1
Width [W]	2.65	±0.1
Height [H]	1.08 MAX	

DM00368430_3

Figure 8. Land pattern and recommended stencil opening

Land pattern



Stencil opening



6.3 RHLGA-5L packing information

Figure 9. Carrier tape and reel mechanical specifications



Specifications: 1. Unmarked tolerance: ±0.1mm; 2. Surface resistance:10⁵-10¹²Ω/SQ, 25±5℃/50±5%RH;

Revision history

Table 9. Document revision history

Date	Version	Changes
13-Oct-2020	1	Initial release

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